

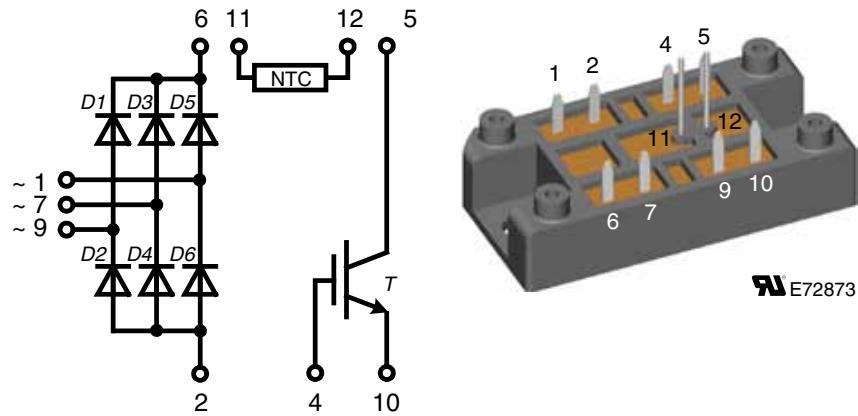
Three Phase Rectifier Bridge with Brake IGBT

$V_{RRM} = 1600 \text{ V}$

$I_{dAVM} = 110 \text{ A}$

Part name (Marking on product)

VUI72-16NOXT



Features:

- Three phase mains rectifier
- Brake IGBT with low saturation voltage

Application:

- Drives with
 - mains input
 - DC link
 - inverter or chopper feeding the machine
 - motor and generator/brake operation

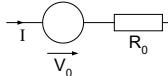
Package:

- High level of integration
- Solder terminals for PCB mounting
- UL registered E72873
- Isolated DCB ceramic base plate
- Large creepage and strike distances
- High reliability

Chopper IGBT T

Symbol	Definitions	Conditions	Ratings			
			min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ\text{C}$ to 150°C		1200		V
V_{GES}	max. DC gate voltage	continuous	-20		+20	V
I_{C25}	collector current	DC	$T_C = 25^\circ\text{C}$		58	A
I_{C80}		DC	$T_C = 80^\circ\text{C}$		40	A
$V_{CE(\text{sat})}$	collector emitter saturation voltage	$I_C = 35 \text{ A}; V_{GE} = 15 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.85 2.15	2.2	V
$V_{GE(\text{th})}$	gate emitter threshold voltage	$I_C = 1 \text{ mA}$	$T_{VJ} = 25^\circ\text{C}$	5.4	6.5	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.1	mA mA	
I_{GES}	gate emitter leakage current	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$		500	nA	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600 \text{ V}; I_C = 35 \text{ A}$ $V_{GE} = \pm 15 \text{ V}; R_G = 27 \Omega; L = 100 \mu\text{H}$		70		ns
t_r	current rise time			40		ns
$t_{d(off)}$	turn-off delay time			250		ns
t_f	current fall time			100		ns
E_{on}	turn-on energy per pulse			3.8		mJ
E_{off}	turn-off energy per pulse			4.1		mJ
Q_{Gon}		$V_{CE} = 600 \text{ V}; V_{GE} = 15 \text{ V}; I_C = 35 \text{ A}$	110			nC
I_{CM}	reverse bias safe operating area	RBSOA; $V_{GE} = \pm 15 \text{ V}; R_G = 27 \Omega; L = 100 \mu\text{H}$	70			A
V_{CEK}		clamped inductive load; $T_{VJ} = 125^\circ\text{C}$	$\leq V_{CES} - L \cdot d_i/dt$			V
t_{sc} (SCSOA)	short circuit safe operating area	$V_{CE} = 900 \text{ V}; V_{GE} = \pm 15 \text{ V}; R_G = 27 \Omega$; non-repetitive	$T_{VJ} = 125^\circ\text{C}$	10		μs
R_{thJC}	thermal resistance junction to case			0.65		K/W
R_{thJH}	thermal resistance case to heatsink	with heat transfer paste, see mounting instructions	0.9			K/W

Equivalent Circuits for Simulation



Symbol	Definitions	Conditions	Ratings			
			min.	typ.	max.	Unit
V_0	Diode	D1 - D6	$T_{VJ} = 125^\circ\text{C}$	0.85 7		V mΩ
R_0						
V_0	IGBT	T	$T_{VJ} = 150^\circ\text{C}$	1.1 40		V mΩ
R_0						

Input Rectifier Diode D1 - D6

Symbol	Conditions	Ratings			
		min.	typ.	max.	
V_{RRM}	max. repetitive reverse voltage			1600	V
I_{FAV}	average forward current	sine 180°	$T_C = 80^\circ\text{C}$	40	A
$I_{D(AV)M}$	max. average DC output current	rectangular; $d = 1/3$; bridge	$T_C = 80^\circ\text{C}$	110	A
I_{FSM}	max. surge forward current	$t = 10 \text{ ms}; \text{sine } 50 \text{ Hz}$	$T_{VJ} = 25^\circ\text{C}$	530	A
P_{tot}	total power dissipation		$T_C = 25^\circ\text{C}$	100	W
I_R	reverse current	$V_R = V_{RRM}$ $V_R = 0.8 \cdot V_{RRM}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	0.02 0.4	mA mA
V_F	forward voltage	$I_F = 25 \text{ A}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	1.0 0.9	V V
R_{thJC}	thermal resistance junction to case	per diode	$T_{VJ} = 25^\circ\text{C}$	1.2	K/W
R_{thJH}	thermal resistance case to heatsink	with heat transfer paste	$T_{VJ} = 25^\circ\text{C}$	1.42	K/W

Temperature Sensor NTC

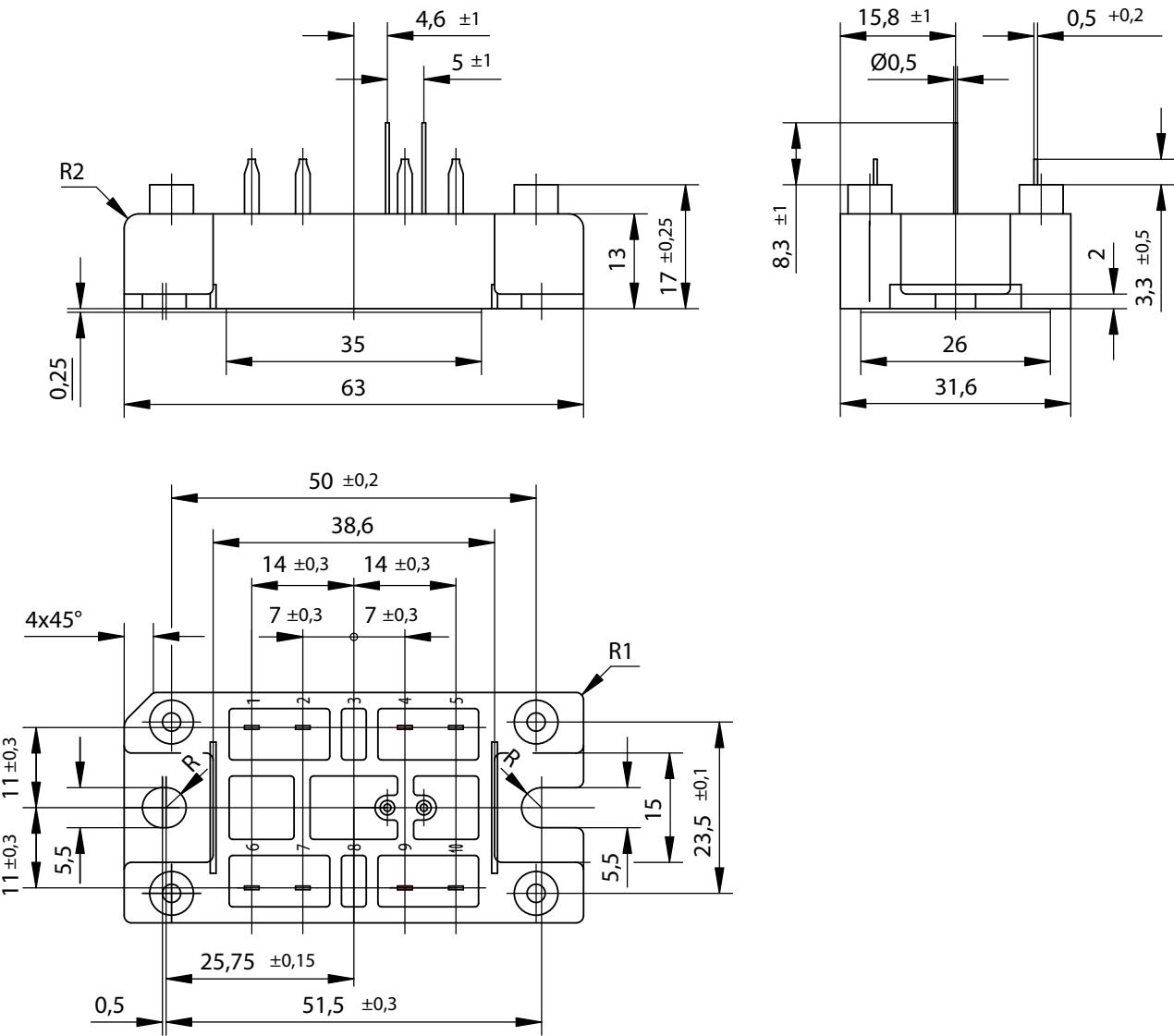
Symbol	Definitions	Conditions	Ratings			
			min.	typ.	max.	Unit
R_{25} $B_{25/100}$	resistance	$\{ R(T) = R_{25} \cdot e^{B_{25/100} \left[\frac{1}{T} - \frac{1}{298K} \right]} \}$	$T = 25^\circ\text{C}$	2.2 3560		$k\Omega$ K

Module

Symbol	Definitions	Conditions	Ratings			
			min.	typ.	max.	Unit
I_{RMS}	RMS current	per pin			100	A
T_{VJ}	operating temperature		-40		150	$^\circ\text{C}$
T_{VJM}	max. virtual junction temperature				150	$^\circ\text{C}$
T_{stg}	storage temperature		-40		125	$^\circ\text{C}$
V_{ISOL}	isolation voltage	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz};$	$t = 1 \text{ min}$		3600	V~
M_d	mounting torque	(M5)	2		2.5	Nm
d_s d_A	creep distance on surface strike distance through air			5 5		mm mm
Weight					35	g

Outline Drawing

Dimensions in mm (1 mm = 0.0394")



Product Marking

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	VUI 72-16NOXT	VUI72-16NOXT	Box	10	510748

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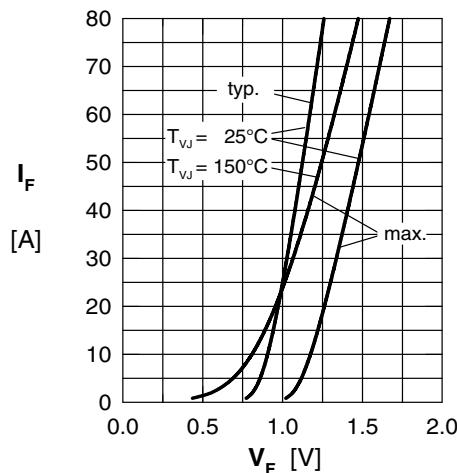


Fig. 1 Forward current vs. voltage drop per rectifier diode

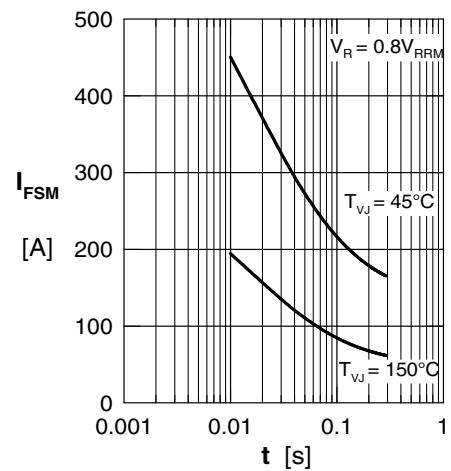


Fig. 2 Surge overload current per rectifier diode

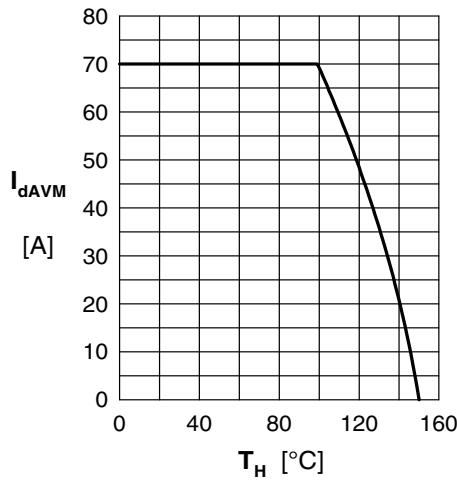


Fig. 3 Max. forward current vs. heatsink temperature (Rectifier bridge)

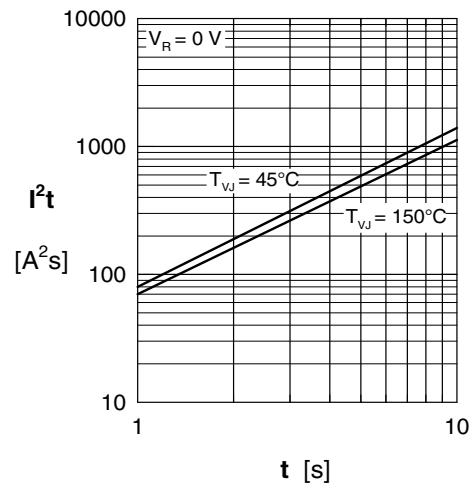


Fig. 4 I^2t versus time per rectifier diode

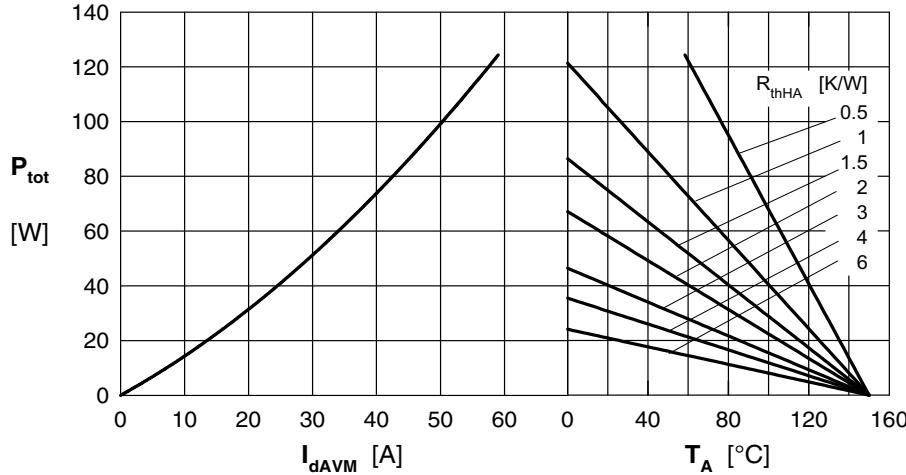


Fig. 5 Power dissipation vs. direct output current & ambient temperature (Rectifier bridge)

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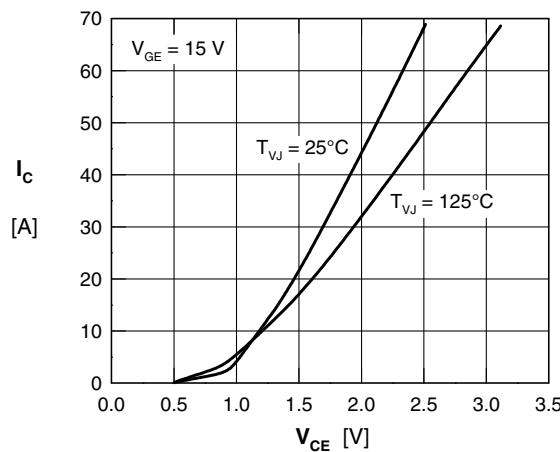


Fig. 6 IGBT, typ. output characteristics

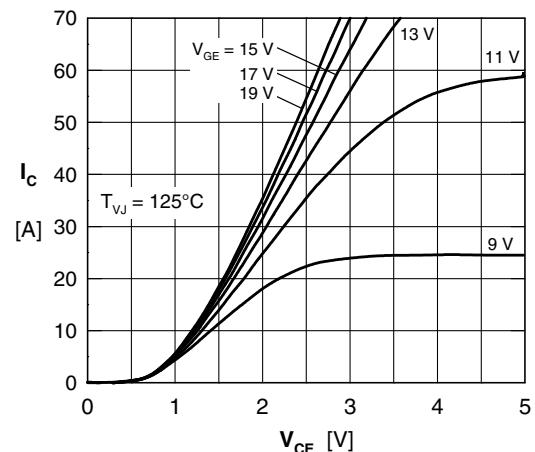


Fig. 7 IGBT, typ. output characteristics

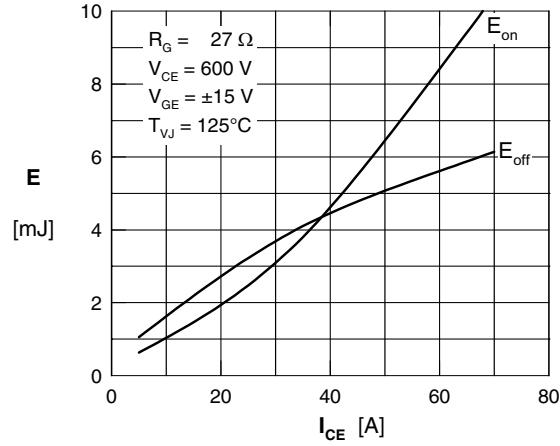


Fig. 8 IGBT, typ. switching energy versus collector current

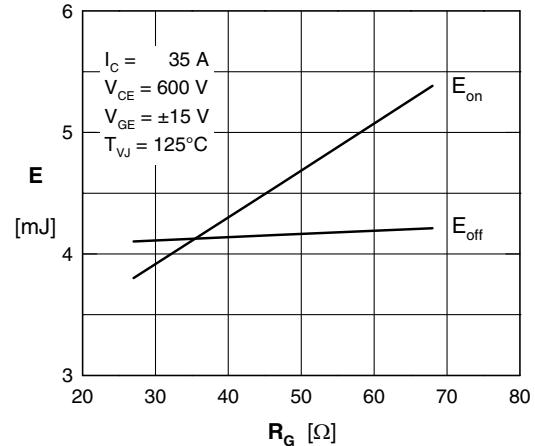


Fig. 9 IGBT, typ. switching energy versus gate resistance

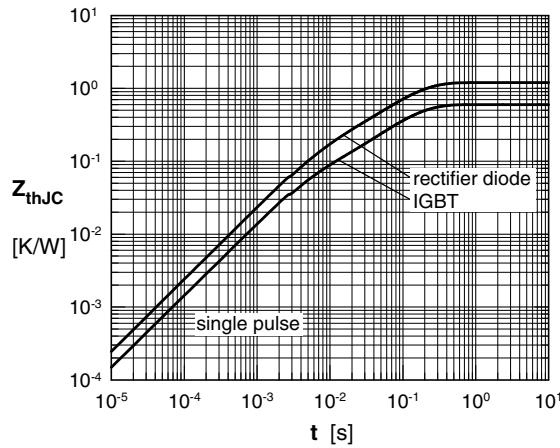


Fig. 10 Typ. transient thermal impedance

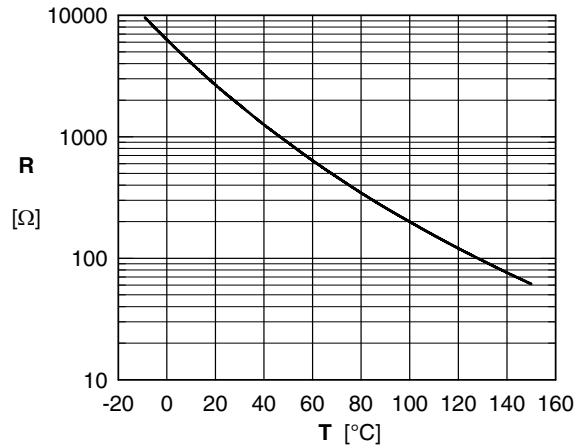


Fig. 11 Typ. thermistor resistance vs. temperature

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